Global Through Silicon Via (TSV) Packaging Market Growth (Status and Outlook) 2025-2031

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Abstracts

According to this study, the global Through Silicon Via (TSV) Packaging market size will reach US$ million by 2031.

Through Silicon Via (TSV) packaging technology enables homogenous and heterogeneous integration of logic and memory co-located closely together in a small form-factor assembly.

The global market for semiconductor was estimated at US$ 579 billion in the year 2022, is projected to US$ 790 billion by 2029, growing at a CAGR of 6% during the forecast period. Although some major categories are still double-digit year-over-year growth in 2022, led by Analog with 20.76%, Sensor with 16.31%, and Logic with 14.46% growth, Memory declined with 12.64% year over year. The microprocessor (MPU) and microcontroller (MCU) segments will experience stagnant growth due to weak shipments and investment in notebooks, computers, and standard desktops. In the current market scenario, the growing popularity of IoT-based electronics is stimulating the need for powerful processors and controllers. Hybrid MPUs and MCUs provide real-time embedded processing and control for the topmost IoT-based applications, resulting in significant market growth. The Analog IC segment is expected to grow gradually, while demand from the networking and communications industries is limited. Few of the emerging trends in the growing demand for Analog integrated circuits include signal conversion, automotive-specific Analog applications, and power management. They drive the growing demand for discrete power devices.

LPI (LP Information)' newest research report, the “Through Silicon Via (TSV) Packaging Industry Forecast” looks at past sales and reviews total world Through Silicon Via (TSV) Packaging sales in 2024, providing a comprehensive analysis by region and market sector of projected Through Silicon Via (TSV) Packaging sales for 2025 through 2031. With Through Silicon Via (TSV) Packaging sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US$ millions of the world Through Silicon Via (TSV) Packaging industry.

This Insight Report provides a comprehensive analysis of the global Through Silicon Via (TSV) Packaging landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyses the strategies of leading global companies with a focus on Through Silicon Via (TSV) Packaging portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global Through Silicon Via (TSV) Packaging market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Through Silicon Via (TSV) Packaging and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global Through Silicon Via (TSV) Packaging.

This report presents a comprehensive overview, market shares, and growth opportunities of Through Silicon Via (TSV) Packaging market by product type, application, key players and key regions and countries.

Segmentation by Type:

2.5D

3D

Segmentation by Application:

Memory Arrays

Image Sensors

- Graphics Chips
- MPUs (Microprocessor Units)
- DRAM (Dynamic Random Access Memory)
- Integrated Circuits
- Others

This report also splits the market by region:

- Americas
  - United States
  - Canada
  - Mexico
  - Brazil
- APAC
  - China
  - Japan
  - Korea
  - Southeast Asia
  - India
  - Australia
- Europe

    - Germany
    - France
    - UK
    - Italy
    - Russia
- Middle East & Africa
    - Egypt
    - South Africa
    - Israel
    - Turkey
    - GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analyzing the company's coverage, product portfolio, its market penetration.

- Applied Materials
- STATS ChipPAC Ltd
- Micralyne, Inc
- Teledyne
- DuPont
- China Wafer Level CSP Co

Samsung Electronics

Amkor Technology

FRT GmbH

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